

## 8102A-4

### 1024 BIT FULLY DECODED STATIC MOS RANDOM ACCESS MEMORY

- Access Time — 450 ns Max.
- Single +5 Volts Supply Voltage
- Directly TTL Compatible — All Inputs and Output
- Static MOS — No Clocks or Refreshing Required
- Low Power — Typically 150 mW
- Three-State Output — OR-Tie Capability
- Simple Memory Expansion — Chip Enable Input
- Fully Decoded — On Chip Address Decode
- Inputs Protected — All Inputs Have Protection Against Static Charge
- Low Cost Packaging — 16 Pin Plastic Dual-In-Line Configuration

The Intel®8102A-4 is a 1024 word by one bit static random access memory element using normally off N-channel MOS devices integrated on a monolithic array. It uses fully DC stable (static) circuitry and therefore requires no clocks or refreshing to operate. The data is read out nondestructively and has the same polarity as the input data.

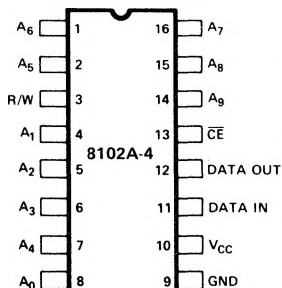
The 8102A-4 is designed for microcomputer memory applications where high performance, low cost, large bit storage, and simple interfacing are important design objectives.

It is directly TTL compatible in all respects: inputs, output, and a single +5 volt supply. A separate chip enable ( $\overline{CE}$ ) lead allows easy selection of an individual package when outputs are OR-tied.

The Intel®8102A-4 is fabricated with N-channel silicon gate technology. This technology allows the design and production of high performance, easy-to-use MOS circuits and provides a higher functional density on a monolithic chip than either conventional MOS technology or P-channel silicon gate technology.

Intel's silicon gate technology also provides excellent protection against contamination. This permits the use of low cost silicone packaging.

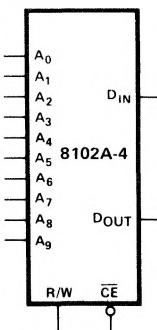
#### PIN CONFIGURATION



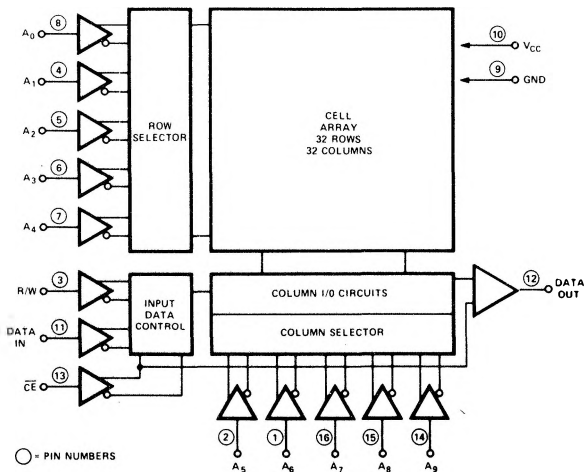
#### PIN NAMES

$D_{IN}$	DATA INPUT	$\overline{CE}$	CHIP ENABLE
$A_0$ - $A_9$	ADDRESS INPUTS	$D_{OUT}$	DATA OUTPUT
R/W	READ/WRITE INPUT	$V_{CC}$	POWER (+5V)

#### LOGIC SYMBOL



#### BLOCK DIAGRAM



## ABSOLUTE MAXIMUM RATINGS\*

Ambient Temperature Under Bias	−10°C to 80°C
Storage Temperature	−65°C to +150°C
Voltage On Any Pin With Respect To Ground	−0.5V to +7V
Power Dissipation	1 Watt

\*COMMENT: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

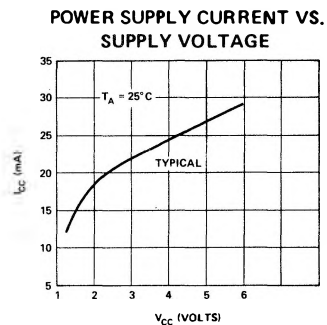
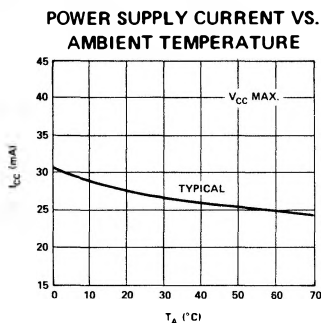
## D.C. AND OPERATING CHARACTERISTICS

$T_A = 0^\circ\text{C}$  to  $+70^\circ\text{C}$ ,  $V_{CC} = 5\text{V} \pm 5\%$  unless otherwise specified

SYMBOL	PARAMETER	LIMITS			UNIT	TEST CONDITIONS
		MIN.	TYP.(1)	MAX.		
$I_{LI}$	INPUT LOAD CURRENT (ALL INPUT PINS)			10	$\mu\text{A}$	$V_{IN} = 0$ to $5.25\text{V}$
$I_{LOH}$	OUTPUT LEAKAGE CURRENT			5	$\mu\text{A}$	$\overline{CE} = 2.0\text{V}$ , $V_{OUT} = 2.4$ to $V_{CC}$
$I_{LOL}$	OUTPUT LEAKAGE CURRENT			−10	$\mu\text{A}$	$\overline{CE} = 2.0\text{V}$ , $V_{OUT} = 0.4\text{V}$
$I_{CC1}$	POWER SUPPLY CURRENT		30	50	mA	ALL INPUTS = $5.25\text{V}$ DATA OUT OPEN $T_A = 25^\circ\text{C}$
$I_{CC2}$	POWER SUPPLY CURRENT			55	mA	ALL INPUTS = $5.25\text{V}$ DATA OUT OPEN $T_A = 0^\circ\text{C}$
$V_{IL}$	INPUT "LOW" VOLTAGE	−0.5		0.8	V	
$V_{IH}$	INPUT "HIGH" VOLTAGE	2.0		$V_{CC}$	V	
$V_{OL}$	OUTPUT "LOW" VOLTAGE			0.4	V	$I_{OL} = 2.1\text{mA}$
$V_{OH}$	OUTPUT "HIGH" VOLTAGE	2.4			V	$I_{OH} = -100\mu\text{A}$

(1) Typical values are for  $T_A = 25^\circ\text{C}$  and nominal supply voltage.

## TYPICAL D.C. CHARACTERISTICS



**A.C. CHARACTERISTICS**  $T_A = 0^\circ\text{C}$  to  $70^\circ\text{C}$ ,  $V_{CC} = 5\text{V} \pm 5\%$  unless otherwise specified

Symbol	Parameter	Limits			Unit
		Min.	Typ.[1]	Max.	
READ CYCLE					
t <sub>RC</sub>	Read Cycle	450			ns
t <sub>A</sub>	Access Time			450	ns
t <sub>CO</sub>	Chip Enable to Output Time			230	ns
t <sub>OH1</sub>	Previous Read Data Valid with Respect to Address	40			ns
t <sub>OH2</sub>	Previous Read Data Valid with Respect to Chip Enable	0			ns
WRITE CYCLE					
t <sub>WC</sub>	Write Cycle	450			ns
t <sub>AW</sub>	Address to Write Setup Time	20			ns
t <sub>WP</sub>	Write Pulse Width	300			ns
t <sub>WR</sub>	Write Recovery Time	0			ns
t <sub>DW</sub>	Data Setup Time	300			ns
t <sub>DH</sub>	Data Hold Time	0			ns
t <sub>CW</sub>	Chip Enable to Write Setup Time	300			ns

NOTE: 1. Typical values are for  $T_A = 25^\circ\text{C}$  and nominal supply voltage.

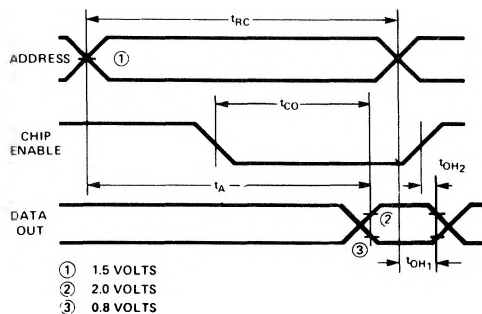
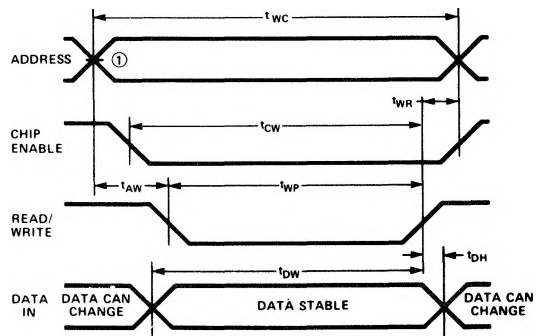
**A. C. CONDITIONS OF TEST**

Input Pulse Levels: 0.8 Volt to 2.0 Volt  
 Input Rise and Fall Times: 10nsec  
 Timing Measurement Inputs: 1.5 Volts  
 Reference Levels Output: 0.8 and 2.0 Volts  
 Output Load: 1 TTL Gate and  $C_L = 100\text{ pF}$

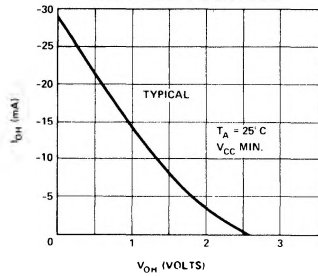
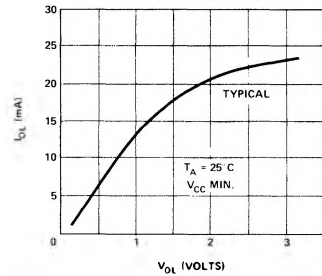
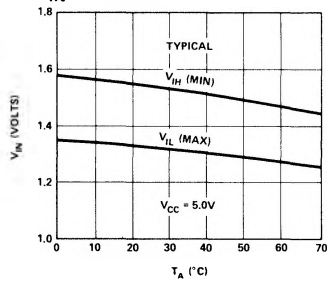
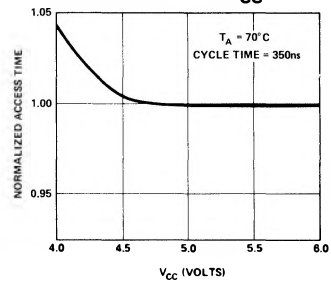
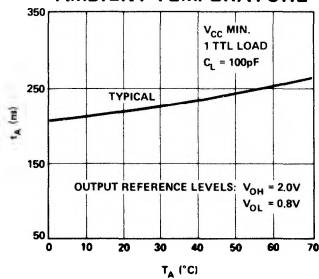
**CAPACITANCE** <sup>[2]</sup>  $T_A = 25^\circ\text{C}$ ,  $f = 1\text{ MHz}$ 

SYMBOL	TEST	LIMITS (pF)	
		TYP.[1]	MAX.
$C_{IN}$	INPUT CAPACITANCE (ALL INPUT PINS) $V_{IN} = 0\text{V}$	3	5
$C_{OUT}$	OUTPUT CAPACITANCE $V_{OUT} = 0\text{V}$	7	10

NOTE: 2. This parameter is periodically sampled and is not 100% tested.

**WAVEFORMS**
**READ CYCLE**

**WRITE CYCLE**


## TYPICAL D.C. AND A.C. CHARACTERISTICS

OUTPUT SOURCE CURRENT VS.  
OUTPUT VOLTAGEOUTPUT SINK CURRENT VS.  
OUTPUT VOLTAGE $V_{IN}$  LIMITS VS. TEMPERATUREACCESS TIME VS.  $V_{CC}$   
NORMALIZED TO  $V_{CC} = 5.0\text{V}$ ACCESS TIME VS.  
AMBIENT TEMPERATUREACCESS TIME VS.  
LOAD CAPACITANCE